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Details

Product Status	Active
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	I ² C, IrDA, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	79
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.62V ~ 3.6V
Data Converters	A/D 16x10b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TFBGA
Supplier Device Package	100-TFBGA (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atsam3n0ca-cur

2. SAM3N Block Diagram

Figure 2-1. SAM3N 100-pin version Block Diagram

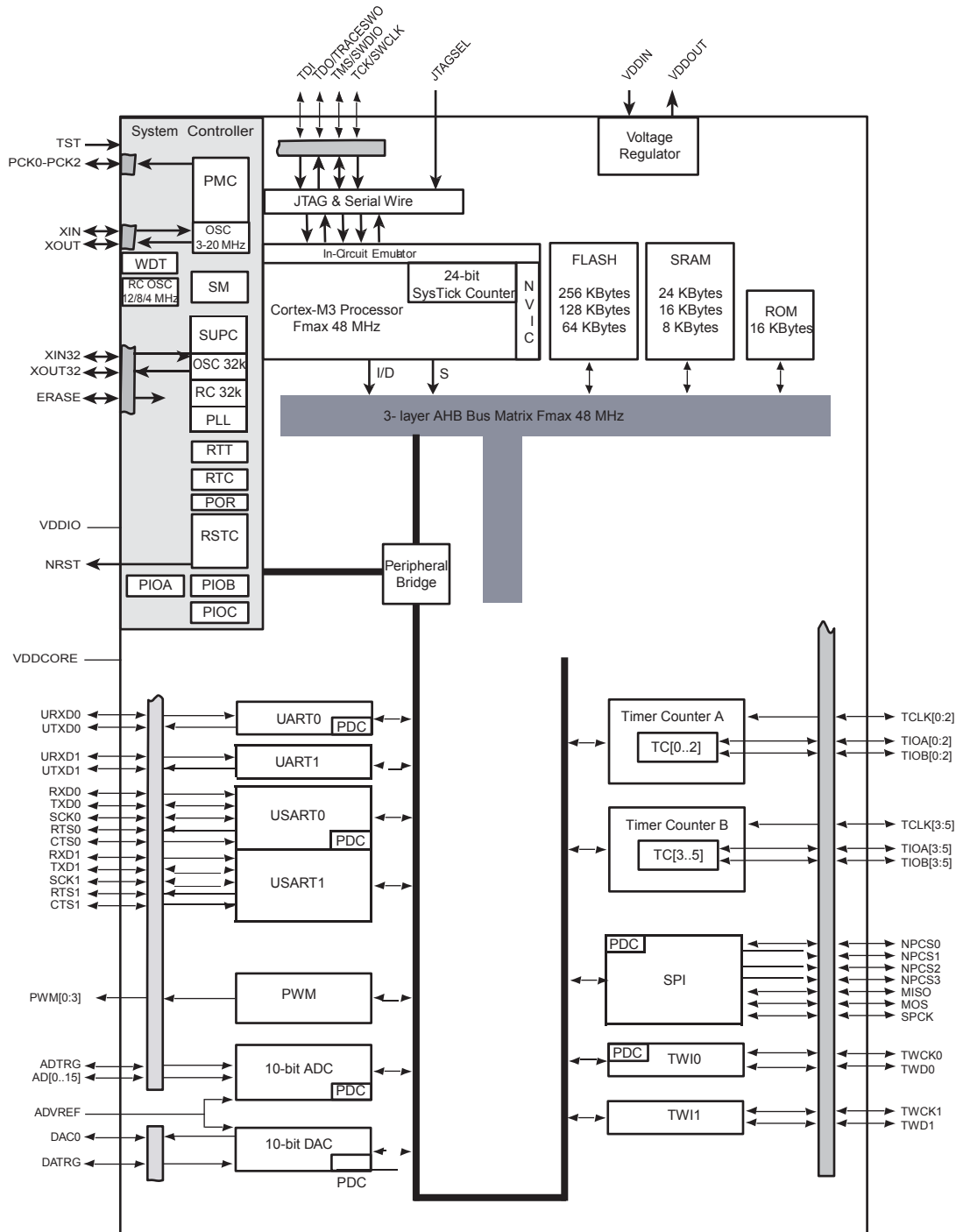


Figure 2-3. SAM3N 48-pin version Block Diagram

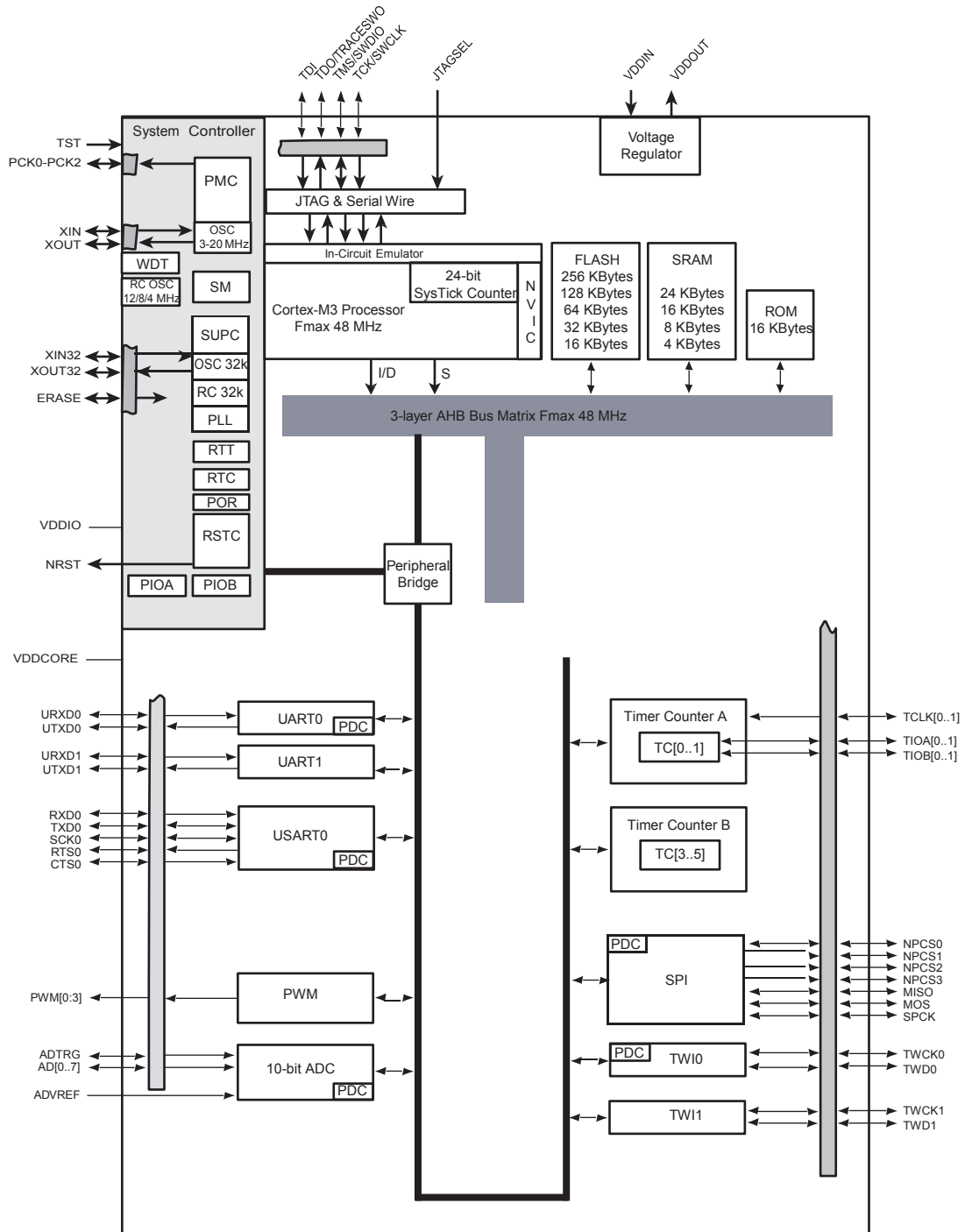


Table 3-1. Signal Description List (Continued)

Signal Name	Function	Type	Active Level	Voltage Reference	Comments
Serial Peripheral Interface - SPI					
MISO	Master In Slave Out	I/O			
MOSI	Master Out Slave In	I/O			
SPCK	SPI Serial Clock	I/O			
SPI_NPCS0	SPI Peripheral Chip Select 0	I/O	Low		
SPI_NPCS1 - SPI_NPCS3	SPI Peripheral Chip Select	Output	Low		
Two-Wire Interface- TWI_x					
TWD _x	TWI _x Two-wire Serial Data	I/O			
TWCK _x	TWI _x Two-wire Serial Clock	I/O			
Analog					
ADVREF	ADC and DAC Reference	Analog			
10-bit Analog-to-Digital Converter - ADC					
AD0 - AD15	Analog Inputs	Analog			
ADTRG	ADC Trigger	Input		VDDIO	
Digital-to-Analog Converter Controller- DACC					
DAC0	DACC channel analog output	Analog			
DATR	DACC Trigger	Input		VDDIO	
Fast Flash Programming Interface					
PGMEN0-PGMEN2	Programming Enabling	Input		VDDIO	
PGMM0-PGMM3	Programming Mode	Input			
PGMD0-PGMD15	Programming Data	I/O			
PGMRDY	Programming Ready	Output	High		
PGMNVALID	Data Direction	Output	Low		
PGMNOE	Programming Read	Input	Low		
PGMCK	Programming Clock	Input			
PGMNCMD	Programming Command	Input	Low		

- Notes:
1. Schmitt Triggers can be disabled through PIO registers.
 2. Some PIO lines are shared with System IOs.
 3. See [Section 5.3 “Typical Powering Schematics”](#) for restriction on voltage range of Analog Cells.

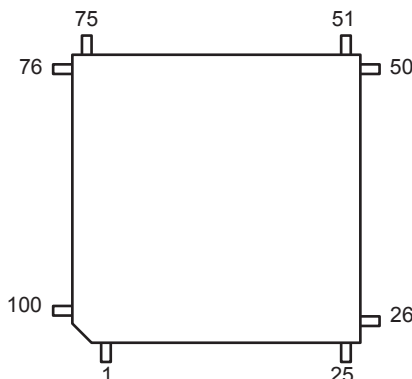
4. Package and Pinout

SAM3N4/2/1/0/00 series is pin-to-pin compatible with SAM3S products. Furthermore SAM3N4/2/1/0/00 devices have new functionalities referenced in *italic* in [Table 4-1](#), [Table 4-3](#) and [Table 4-4](#).

4.1 SAM3N4/2/1/0/00C Package and Pinout

4.1.1 100-lead LQFP Package Outline

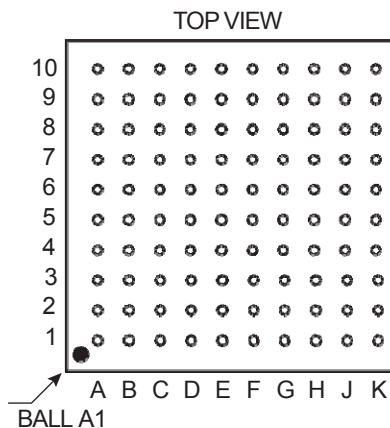
Figure 4-1. Orientation of the 100-lead LQFP Package



4.1.2 100-ball TFBGA Package Outline

The 100-Ball TFBGA package has a 0.8 mm ball pitch and respects Green Standards. Its dimensions are 9 x 9 x 1.1 mm.

Figure 4-2. Orientation of the 100-ball TFBGA Package



4.1.3 100-Lead LQFP Pinout

Table 4-1. 100-lead LQFP SAM3N4/2/1/0/00C Pinout

1	ADVREF	26	GND	51	TDI/PB4	76	TDO/TRACESWO/PB5
2	GND	27	VDDIO	52	PA6/PGMNOE	77	JTAGSEL
3	PB0/AD4	28	PA16/PGMD4	53	PA5/PGMRDY	78	PC18
4	PC29/AD13	29	PC7	54	PC28	79	TMS/SWDIO/PB6
5	PB1/AD5	30	PA15/PGMD3	55	PA4/PGMNCMD	80	PC19
6	PC30/AD14	31	PA14/PGMD2	56	VDDCORE	81	PA31
7	PB2/AD6	32	PC6	57	PA27	82	PC20
8	PC31/AD15	33	PA13/PGMD1	58	PC8	83	TCK/SWCLK/PB7
9	PB3/AD7	34	PA24	59	PA28	84	PC21
10	VDDIN	35	PC5	60	NRST	85	VDDCORE
11	VDDOUT	36	VDDCORE	61	TST	86	PC22
12	PA17/PGMD5/AD0	37	PC4	62	PC9	87	ERASE/PB12
13	PC26	38	PA25	63	PA29	88	PB10
14	PA18/PGMD6/AD1	39	PA26	64	PA30	89	PB11
15	PA21/AD8	40	PC3	65	PC10	90	PC23
16	VDDCORE	41	PA12/PGMD0	66	PA3	91	VDDIO
17	PC27	42	PA11/PGMM3	67	PA2/PGMEN2	92	PC24
18	PA19/PGMD7/AD2	43	PC2	68	PC11	93	PB13/DAC0
19	PC15/AD11	44	PA10/PGMM2	69	VDDIO	94	PC25
20	PA22/AD9	45	GND	70	GND	95	GND
21	PC13/AD10	46	PA9/PGMM1	71	PC14	96	PB8/XOUT
22	PA23	47	PC1	72	PA1/PGMEN1	97	PB9/PGMCK/XIN
23	PC12/AD12	48	PA8/XOUT32/ PGMM0	73	PC16	98	VDDIO
24	PA20/AD3	49	PA7/XIN32/ PGMINVALID	74	PA0/PGMEN0	99	PB14
25	PC0	50	VDDIO	75	PC17	100	VDDPLL

4.1.4 100-ball TFBGA Pinout

Table 4-2. 100-ball TFBGA SAM3N4/2/1/0/00C Pinout

A1	PB1	C6	PB7	F1	PA18	H6	PC4
A2	PC29	C7	PC16	F2	PC26	H7	PA11
A3	VDDIO	C8	PA1	F3	VDDOUT	H8	PC1
A4	PB9	C9	PC17	F4	GND	H9	PA6
A5	PB8	C10	PA0	F5	VDDIO	H10	PB4
A6	PB13	D1	PB3	F6	PA27	J1	PC15
A7	PB11	D2	PB0	F7	PC8	J2	PC0
A8	PB10	D3	PC24	F8	PA28	J3	PA16
A9	PB6	D4	PC22	F9	TST	J4	PC6
A10	JTAGSEL	D5	GND	F10	PC9	J5	PA24
B1	PC30	D6	GND	G1	PA21	J6	PA25
B2	ADVREF	D7	VDDCORE	G2	PC27	J7	PA10
B3	GNDANA	D8	PA2	G3	PA15	J8	GND
B4	PB14	D9	PC11	G4	VDDCORE	J9	VDDCORE
B5	PC21	D10	PC14	G5	VDDCORE	J10	VDDIO
B6	PC20	E1	PA17	G6	PA26	K1	PA22
B7	PA31	E2	PC31	G7	PA12	K2	PC13
B8	PC19	E3	VDDIN	G8	PC28	K3	PC12
B9	PC18	E4	GND	G9	PA4	K4	PA20
B10	PB5	E5	GND	G10	PA5	K5	PC5
C1	PB2	E6	NRST	H1	PA19	K6	PC3
C2	VDDPLL	E7	PA29	H2	PA23	K7	PC2
C3	PC25	E8	PA30	H3	PC7	K8	PA9
C4	PC23	E9	PC10	H4	PA14	K9	PA8
C5	PB12	E10	PA3	H5	PA13	K10	PA7

4.2.1 64-Lead LQFP and QFN Pinout

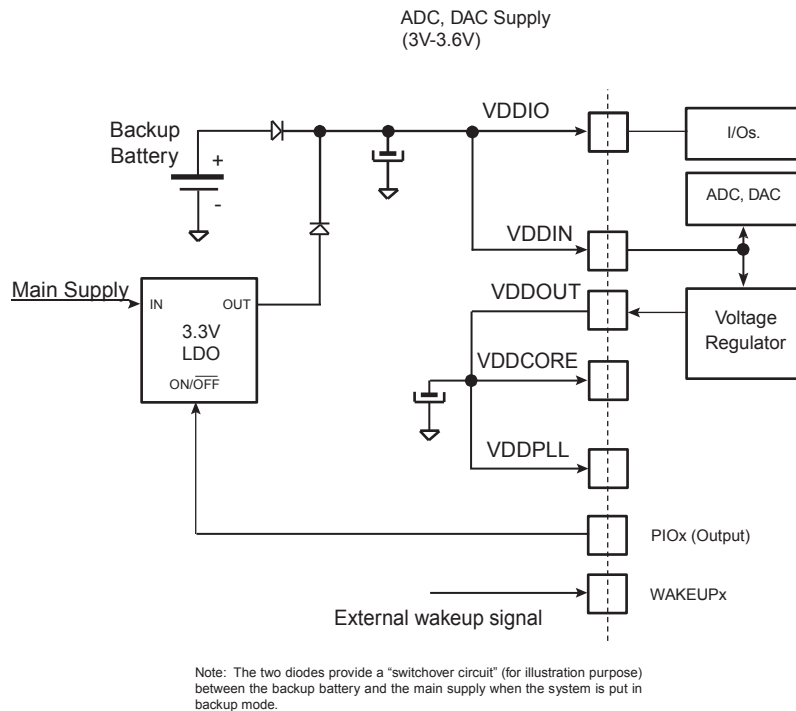
64-pin version SAM3N devices are pin-to-pin compatible with SAM3S products. Furthermore, SAM3N products have new functionalities shown in *italic* in [Table 4-3](#).

Table 4-3. 64-pin SAM3N4/2/1/0/00B Pinout

1	ADVREF	17	GND	33	<i>TDI/PB4</i>	49	<i>TDO/TRACESWO/PB5</i>
2	GND	18	VDDIO	34	PA6/PGMNOE	50	JTAGSEL
3	<i>PB0/AD4</i>	19	PA16/PGMD4	35	PA5/PGMRDY	51	<i>TMS/SWDIO/PB6</i>
4	<i>PB1AD5</i>	20	PA15/PGMD3	36	PA4/PGMNCMD	52	PA31
5	<i>PB2/AD6</i>	21	PA14/PGMD2	37	PA27/PGMD15	53	<i>TCK/SWCLK/PB7</i>
6	<i>PB3/AD7</i>	22	PA13/PGMD1	38	PA28	54	VDDCORE
7	VDDIN	23	PA24/PGMD12	39	NRST	55	<i>ERASE/PB12</i>
8	VDDOUT	24	VDDCORE	40	TST	56	<i>PB10</i>
9	PA17/PGMD5/AD0	25	PA25/PGMD13	41	PA29	57	<i>PB11</i>
10	PA18/PGMD6/AD1	26	PA26/PGMD14	42	PA30	58	VDDIO
11	PA21/PGMD9/AD8	27	PA12/PGMD0	43	PA3	59	<i>PB13/DAC0</i>
12	VDDCORE	28	PA11/PGMM3	44	PA2/PGMEN2	60	GND
13	PA19/PGMD7/AD2	29	PA10/PGMM2	45	VDDIO	61	<i>XOUT/PB8</i>
14	PA22/PGMD10/AD9	30	PA9/PGMM1	46	GND	62	<i>XIN/PGMCK/PB9</i>
15	PA23/PGMD11	31	PA8/XOUT32/PGMM0	47	PA1/PGMEN1	63	<i>PB14</i>
16	PA20/PGMD8/AD3	32	PA7/XIN32/XOUT32/PGMNVALID	48	PA0/PGMEN0	64	VDDPLL

Note: The bottom pad of the QFN package must be connected to ground.

Figure 5-3. Core Externally Supplied (backup battery)



5.4 Active Mode

Active mode is the normal running mode with the core clock running from the fast RC oscillator, the main crystal oscillator or the PLL. The power management controller can be used to adapt the frequency and to disable the peripheral clocks.

5.5 Low Power Modes

The various low-power modes of the SAM3N are described below:

5.5.1 Backup Mode

The purpose of backup mode is to achieve the lowest power consumption possible in a system that is performing periodic wakeups to carry out tasks but not requiring fast startup time (<0.1ms). Total current consumption is 3 μ A typical.

The Supply Controller, zero-power power-on reset, RTT, RTC, Backup registers and 32 kHz oscillator (RC or crystal oscillator selected by software in the Supply Controller) are running. The regulator and the core supply are off.

Backup mode is based on the Cortex-M3 deep sleep mode with the voltage regulator disabled.

The SAM3N can be awakened from this mode through WUP0-15 pins, the supply monitor (SM), the RTT or RTC wake-up event.

Backup mode is entered by using WFE instructions with the SLEEPDEEP bit in the System Control Register of the Cortex-M3 set to 1. (See the Power management description in The ARM Cortex M3 Processor section of the product datasheet).

Exit from Backup mode happens if one of the following enable wake-up events occurs:

- WKUPEN0-15 pins (level transition, configurable debouncing)

5.5.4 Low Power Mode Summary Table

The modes detailed above are the main low power modes. Each part can be set to on or off separately and wake up sources can be individually configured. [Table 5-1](#) below shows a summary of the configurations of the low power modes.

Table 5-1. Low Power Mode Configuration Summary

Mode	SUPC, 32 kHz Oscillator RTC RTT Backup Registers, POR (Backup Region)	Regulator	Core Memory Peripherals	Mode Entry	Potential Wake Up Sources	Core at Wake Up	PIO State while in Low Power Mode	PIO State at Wake Up	Consumption ^{(2) (3)}	Wake Up Time ⁽¹⁾
Backup Mode	ON	OFF	OFF (Not powered)	WFE +SLEEPDEEP bit = 1	WUP0-15 pins BOD alarm RTC alarm RTT alarm	Reset	Previous state saved	PIOA & PIOB & PIOC Inputs with pull ups	3 μ A typ ⁽⁴⁾	< 0.1 ms
Wait Mode	ON	ON	Powered (Not clocked)	WFE +SLEEPDEEP bit = 0 +LPM bit = 1	Any Event from: Fast startup through WUP0-15 pins RTC alarm RTT alarm	Clocked back	Previous state saved	Unchanged	5 μ A/15 μ A ⁽⁵⁾	< 10 μ s
Sleep Mode	ON	ON	Powered ⁽⁷⁾ (Not clocked)	WFE or WFI +SLEEPDEEP bit = 0 +LPM bit = 0	Entry mode = WFI Interrupt Only; Entry mode = WFE Any Enabled Interrupt and/or Any Event from: Fast start-up through WUP0-15 pins RTC alarm RTT alarm	Clocked back	Previous state saved	Unchanged ⁽⁶⁾	⁽⁶⁾	⁽⁶⁾

- Notes:
1. When considering wake-up time, the time required to start the PLL is not taken into account. Once started, the device works with the 4/8/12 MHz Fast RC oscillator. The user has to add the PLL start-up time if it is needed in the system. The wake-up time is defined as the time taken for wake up until the first instruction is fetched.
 2. The external loads on PIOs are not taken into account in the calculation.
 3. Supply Monitor current consumption is not included.
 4. Total Current consumption.
 5. 5 μ A on VDDCORE, 15 μ A for total current consumption (using internal voltage regulator), 8 μ A for total current consumption (without using internal voltage regulator).
 6. Depends on MCK frequency.
 7. In this mode the core is supplied and not clocked but some peripherals can be clocked.

5.7 Fast Start-Up

The SAM3N allows the processor to restart in a few microseconds while the processor is in wait mode. A fast start up can occur upon detection of a low level on one of the 19 wake-up inputs (WKUP0 to 15 + SM + RTC + RTT).

The fast restart circuitry, as shown in [Figure 5-5](#), is fully asynchronous and provides a fast start-up signal to the Power Management Controller. As soon as the fast start-up signal is asserted, the PMC automatically restarts the embedded 4 MHz fast RC oscillator, switches the master clock on this 4 MHz clock and reenables the processor clock.

Figure 5-5. Fast Start-Up Sources

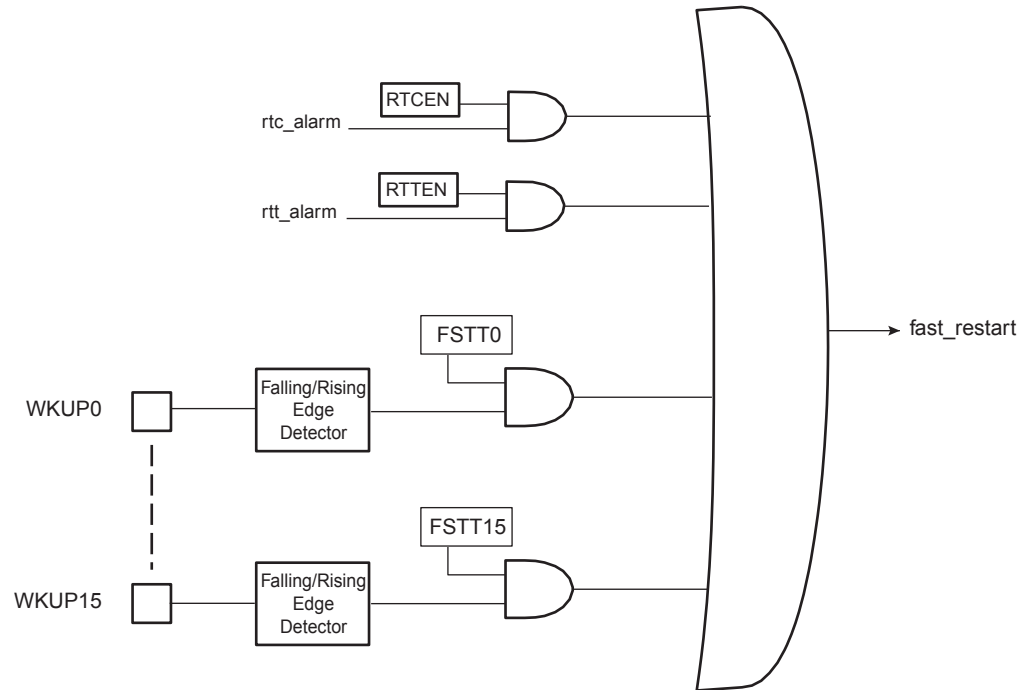


Table 6-1. System I/O Configuration Pin List.

SYSTEM_IO bit number	Default function after reset	Other function	Constraints for normal start	Configuration
12	ERASE	PB12	Low Level at startup ⁽¹⁾	In Matrix User Interface Registers (Refer to the System I/O Configuration Register in the Bus Matrix section of the product datasheet.)
7	TCK/SWCLK	PB7	-	
6	TMS/SWDIO	PB6	-	
5	TDO/TRACESWO	PB5	-	
4	TDI	PB4	-	
-	PA7	XIN32	-	See footnote ⁽²⁾ below
-	PA8	XOUT32	-	
-	PB9	XIN	-	See footnote ⁽³⁾ below
-	PB8	XOUT	-	

Notes: 1. If PB12 is used as PIO input in user applications, a low level must be ensured at startup to prevent Flash erase before the user application sets PB12 into PIO mode.
2. In the product Datasheet Refer to: Slow Clock Generator of the Supply Controller section.
3. In the product Datasheet Refer to: 3 to 20 MHZ Crystal Oscillator information in the PMC section.

6.2.1 Serial Wire JTAG Debug Port (SWJ-DP) Pins

The SWJ-DP pins are TCK/SWCLK, TMS/SWDIO, TDO/SWO, TDI and commonly provided on a standard 20-pin JTAG connector defined by ARM. For more details about voltage reference and reset state, refer to [Table 3-1 on page 7](#).

At startup, SWJ-DP pins are configured in SWJ-DP mode to allow connection with debugging probe. Please refer to the Debug and Test Section of the product datasheet.

SWJ-DP pins can be used as standard I/Os to provide users more general input/output pins when the debug port is not needed in the end application. Mode selection between SWJ-DP mode (System IO mode) and general IO mode is performed through the AHB Matrix Special Function Registers (MATRIX_SFR). Configuration of the pad for pull-up, triggers, debouncing and glitch filters is possible regardless of the mode.

The JTAGSEL pin is used to select the JTAG boundary scan when asserted at a high level. It integrates a permanent pull-down resistor of about 15 kΩ to GND, so that it can be left unconnected for normal operations.

By default, the JTAG Debug Port is active. If the debugger host wants to switch to the Serial Wire Debug Port, it must provide a dedicated JTAG sequence on TMS/SWDIO and TCK/SWCLK which disables the JTAG-DP and enables the SW-DP. When the Serial Wire Debug Port is active, TDO/TRACESWO can be used for trace.

The asynchronous TRACE output (TRACESWO) is multiplexed with TDO. So the asynchronous trace can only be used with SW-DP, not JTAG-DP. For more information about SW-DP and JTAG-DP switching, please refer to the Debug and Test Section.

6.3 Test Pin

The TST pin is used for JTAG Boundary Scan Manufacturing Test or Fast Flash programming mode of the SAM3N series. The TST pin integrates a permanent pull-down resistor of about 15 k Ω to GND, so that it can be left unconnected for normal operations. To enter fast programming mode, see the Fast Flash Programming Interface (FFPI) section. For more on the manufacturing and test mode, refer to the “Debug and Test” section of the product datasheet.

6.4 NRST Pin

The NRST pin is bidirectional. It is handled by the on-chip reset controller and can be driven low to provide a reset signal to the external components or asserted low externally to reset the microcontroller. It will reset the Core and the peripherals except the Backup region (RTC, RTT and Supply Controller). There is no constraint on the length of the reset pulse and the reset controller can guarantee a minimum pulse length. The NRST pin integrates a permanent pull-up resistor to VDDIO of about 100 k Ω . By default, the NRST pin is configured as an input.

6.5 ERASE Pin

The ERASE pin is used to reinitialize the Flash content (and some of its NVM bits) to an erased state (all bits read as logic level 1). It integrates a pull-down resistor of about 100 k Ω to GND, so that it can be left unconnected for normal operations.

This pin is debounced by SCLK to improve the glitch tolerance. When the ERASE pin is tied high during less than 100 ms, it is not taken into account. The pin must be tied high during more than 220 ms to perform a Flash erase operation.

The ERASE pin is a system I/O pin and can be used as a standard I/O. At startup, the ERASE pin is not configured as a PIO pin. If the ERASE pin is used as a standard I/O, startup level of this pin must be low to prevent unwanted erasing. Please refer to [Section 11.2 “Peripheral Signals Multiplexing on I/O Lines” on page 42](#). Also, if the ERASE pin is used as a standard I/O output, asserting the pin to low does not erase the Flash.

7. Processor and Architecture

7.1 ARM Cortex-M3 Processor

- Version 2.0
- Thumb-2 (ISA) subset consisting of all base Thumb-2 instructions, 16-bit and 32-bit.
- Harvard processor architecture enabling simultaneous instruction fetch with data load/store.
- Three-stage pipeline.
- Single cycle 32-bit multiply.
- Hardware divide.
- Thumb and Debug states.
- Handler and Thread modes.
- Low latency ISR entry and exit.

7.2 APB/AHB Bridge

The SAM3N4/2/1/0/00 product embeds one peripheral bridge:

The peripherals of the bridge are clocked by MCK.

7.3 Matrix Masters

The Bus Matrix of the SAM3N product manages 3 masters, which means that each master can perform an access concurrently with others, to an available slave.

Each master has its own decoder, which is defined specifically for each master. In order to simplify the addressing, all the masters have the same decodings.

Table 7-1. List of Bus Matrix Masters

Master 0	Cortex-M3 Instruction/Data
Master 1	Cortex-M3 System
Master 2	Peripheral DMA Controller (PDC)

7.4 Matrix Slaves

The Bus Matrix of the SAM3N product manages 4 slaves. Each slave has its own arbiter, allowing a different arbitration per slave.

Table 7-2. List of Bus Matrix Slaves

Slave 0	Internal SRAM
Slave 1	Internal ROM
Slave 2	Internal Flash
Slave 3	Peripheral Bridge

7.7 Debug and Test Features

- Debug access to all memory and registers in the system, including Cortex-M3 register bank when the core is running, halted, or held in reset.
- Serial Wire Debug Port (SW-DP) and Serial Wire JTAG Debug Port (SWJ-DP) debug access
- Flash Patch and Breakpoint (FPB) unit for implementing breakpoints and code patches
- Data Watchpoint and Trace (DWT) unit for implementing watchpoints, data tracing, and system profiling
- Instrumentation Trace Macrocell (ITM) for support of printf style debugging
- IEEE1149.1 JTAG Boundary-scan on All Digital Pins

10.6 Power Management Controller

The Power Management Controller provides all the clock signals to the system. It provides:

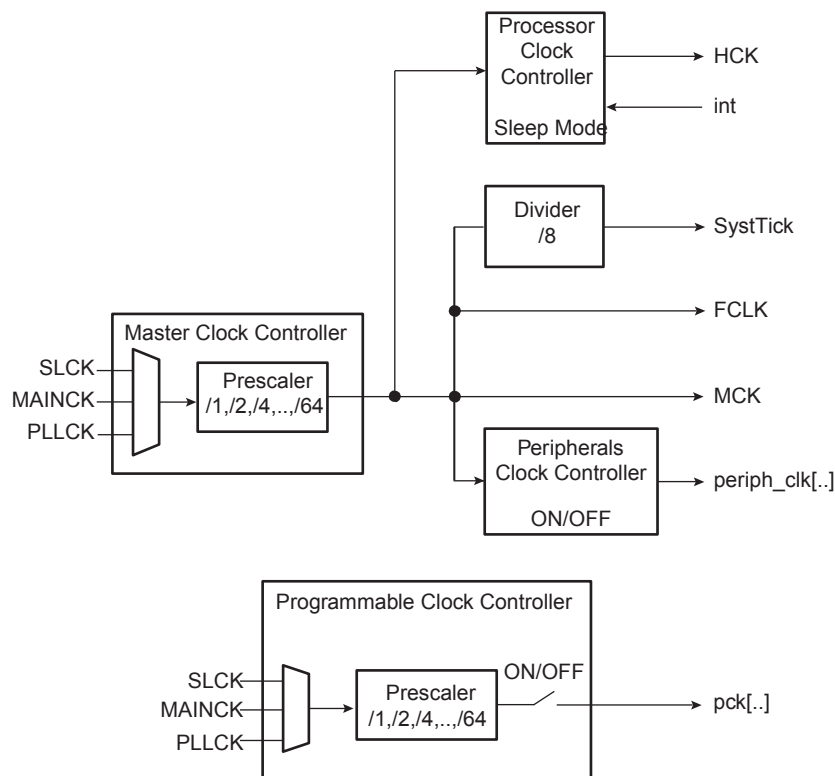
- the Processor Clock HCLK
- the Free running processor clock FCLK
- the Cortex SysTick external clock
- the Master Clock MCK, in particular to the Matrix and the memory interfaces
- independent peripheral clocks, typically at the frequency of MCK
- three programmable clock outputs: PCK0, PCK1 and PCK2

The Supply Controller selects between the 32 kHz RC oscillator or the crystal oscillator. The unused oscillator is disabled automatically so that power consumption is optimized.

By default, at startup the chip runs out of the Master Clock using the Fast RC Oscillator running at 4 MHz.

The user can trim by software the 8 and 12 MHz RC Oscillator frequency.

Figure 10-3. SAM3N4/2/1/0/00 Power Management Controller Block Diagram



The SysTick calibration value is fixed at 6000 which allows the generation of a time base of 1 ms with SysTick clock at 6 MHz (48 MHz/8)

10.7 Watchdog Timer

- 16-bit key-protected only-once-Programmable Counter
- Windowed, prevents the processor to be in a dead-lock on the watchdog access

11.2.1 PIO Controller A Multiplexing

Table 11-2. Multiplexing on PIO Controller A (PIOA)

I/O Line	Peripheral A	Peripheral B	Peripheral C	Extra Function	System Function	Comments
PA0	PWM0	TIOA0		WKUP0		High drive
PA1	PWM1	TIOB0		WKUP1		High drive
PA2	PWM2	SCK0	DATRG	WKUP2		High drive
PA3	TWD0	NPCS3				High drive
PA4	TWCK0	TCLK0		WKUP3		
PA5	RXD0	NPCS3		WKUP4		
PA6	TXD0	PCK0				
PA7	RTS0	PWM3			XIN32	
PA8	CTS0	ADTRG		WKUP5	XOUT32	
PA9	URXD0	NPCS1		WKUP6		
PA10	UTXD0	NPCS2				
PA11	NPCS0	PWM0		WKUP7		
PA12	MISO	PWM1				
PA13	MOSI	PWM2				
PA14	SPCK	PWM3		WKUP8		
PA15		TIOA1		WKUP14		
PA16		TIOB1		WKUP15		
PA17		PCK1		AD0		
PA18		PCK2		AD1		
PA19				AD2/WKUP9		
PA20				AD3/WKUP10		
PA21	RXD1	PCK1		AD8		64/100-pin versions
PA22	TXD1	NPCS3		AD9		64/100-pin versions
PA23	SCK1	PWM0				64/100-pin versions
PA24	RTS1	PWM1				64/100-pin versions
PA25	CTS1	PWM2				64/100-pin versions
PA26		TIOA2				64/100-pin versions
PA27		TIOB2				64/100-pin versions
PA28		TCLK1				64/100-pin versions
PA29		TCLK2				64/100-pin versions
PA30		NPCS2		WKUP11		64/100-pin versions
PA31	NPCS1	PCK2				64/100-pin versions

Figure 13-2. 100-ball TFBGA Package Drawing

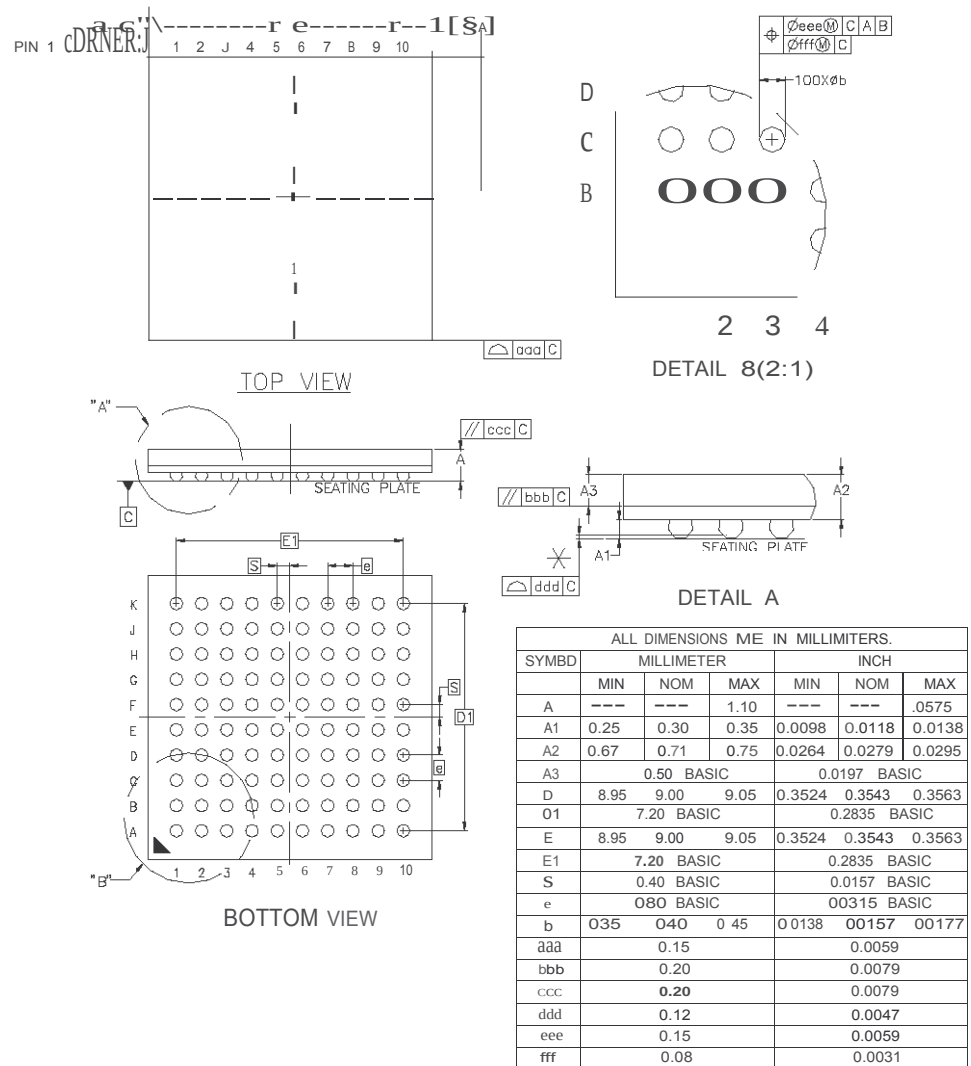


Table 13-1. 48-lead LQFP Package Dimensions (in mm)

Symbol	Millimeter			Inch		
	Min	Nom	Max	Min	Nom	Max
A	—	—	1.60	—	—	0.063
A1	0.05	—	0.15	0.002	—	0.006
A2	1.35	1.40	1.45	0.053	0.055	0.057
D	9.00 BSC			0.354 BSC		
D1	7.00 BSC			0.276 BSC		
E	9.00 BSC			0.354 BSC		
E1	7.00 BSC			0.276 BSC		
R2	0.08	—	0.20	0.003	—	0.008
R1	0.08	—	—	0.003	—	—
q	0°	3.5°	7°	0°	3.5°	7°
θ ₁	0°	—	—	0°	—	—
θ ₂	11°	12°	13°	11°	12°	13°
θ ₃	11°	12°	13°	11°	12°	13°
c	0.09	—	0.20	0.004	—	0.008
L	0.45	0.60	0.75	0.018	0.024	0.030
L1	1.00 REF			0.039 REF		
S	0.20	—	—	0.008	—	—
b	0.17	0.20	0.27	0.007	0.008	0.011
e	0.50 BSC.			0.020 BSC.		
D2	5.50			0.217		
E2	5.50			0.217		
Tolerances of Form and Position						
aaa	0.20			0.008		
bbb	0.20			0.008		
ccc	0.08			0.003		
ddd	0.08			0.003		

Table 13-2. 64-lead LQFP Package Dimensions (in mm)

Symbol	Millimeter			Inch		
	Min	Nom	Max	Min	Nom	Max
A	—	—	1.60	—	—	0.063
A1	0.05	—	0.15	0.002	—	0.006
A2	1.35	1.40	1.45	0.053	0.055	0.057
D	12.00 BSC			0.472 BSC		
D1	10.00 BSC			0.383 BSC		
E	12.00 BSC			0.472 BSC		
E1	10.00 BSC			0.383 BSC		
R2	0.08	—	0.20	0.003	—	0.008
R1	0.08	—	—	0.003	—	—
q	0°	3.5°	7°	0°	3.5°	7°
θ ₁	0°	—	—	0°	—	—
θ ₂	11°	12°	13°	11°	12°	13°
θ ₃	11°	12°	13°	11°	12°	13°
c	0.09	—	0.20	0.004	—	0.008
L	0.45	0.60	0.75	0.018	0.024	0.030
L1	1.00 REF			0.039 REF		
S	0.20	—	—	0.008	—	—
b	0.17	0.20	0.27	0.007	0.008	0.011
e	0.50 BSC.			0.020 BSC.		
D2	7.50			0.285		
E2	7.50			0.285		
Tolerances of Form and Position						
aaa	0.20			0.008		
bbb	0.20			0.008		
ccc	0.08			0.003		
ddd	0.08			0.003		

14. Ordering Information

Table 14-1.

Ordering Code	MRL	Flash (Kbytes)	Package	Package Type	Temperature Operating Range
ATSAM3N4CA-AU	A	256	LQFP100	Green	Industrial -40°C to 85°C
ATSAM3N4CA-CU	A	256	TFBGA100	Green	Industrial -40°C to 85°C
ATSAM3N4BA-AU	A	256	LQFP64	Green	Industrial -40°C to 85°C
ATSAM3N4BA-MU	A	256	QFN64	Green	Industrial -40°C to 85°C
ATSAM3N4AA-AU	A	256	LQFP48	Green	Industrial -40°C to 85°C
ATSAM3N4AA-MU	A	256	QFN48	Green	Industrial -40°C to 85°C
ATSAM3N2CA-AU	A	128	LQFP100	Green	Industrial -40°C to 85°C
ATSAM3N2CA-CU	A	128	TFBGA100	Green	Industrial -40°C to 85°C
ATSAM3N2BA-AU	A	128	LQFP64	Green	Industrial -40°C to 85°C
ATSAM3N2BA-MU	A	128	QFN64	Green	Industrial -40°C to 85°C
ATSAM3N2AA-AU	A	128	LQFP48	Green	Industrial -40°C to 85°C
ATSAM3N2AA-MU	A	128	QFN48	Green	Industrial -40°C to 85°C
ATSAM3N1CA-AU	A	64	LQFP100	Green	Industrial -40°C to 85°C
ATSAM3N1CB-AU	B	64	LQFP100	Green	Industrial -40°C to 85°C
ATSAM3N1CA-CU	A	64	TFBGA100	Green	Industrial -40°C to 85°C
ATSAM3N1CB-CU	B	64	TFBGA100	Green	Industrial -40°C to 85°C
ATSAM3N1BA-AU	A	64	LQFP64	Green	Industrial -40°C to 85°C
ATSAM3N1BB-AU	B	64	LQFP64	Green	Industrial -40°C to 85°C
ATSAM3N1BA-MU	A	64	QFN 64	Green	Industrial -40°C to 85°C
ATSAM3N1BB-MU	B	64	QFN 64	Green	Industrial -40°C to 85°C